

# TCA0372, TCA0372B, NCV0372B



**ON Semiconductor®**

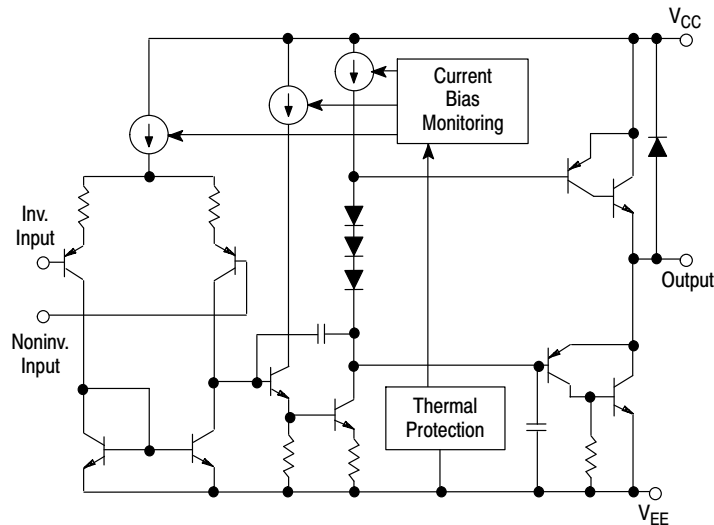
<http://onsemi.com>

## 1.0 A Output Current, Dual Power Operational Amplifiers

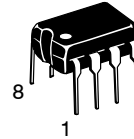
The TCA0372 is a monolithic circuit intended for use as a power operational amplifier in a wide range of applications, including servo amplifiers and power supplies. No deadband crossover distortion provides better performance for driving coils.

### Features

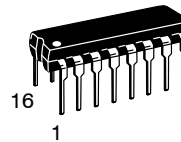
- Output Current to 1.0 A
- Slew Rate of 1.3 V/ $\mu$ s
- Wide Bandwidth of 1.1 MHz
- Internal Thermal Shutdown
- Single or Split Supply Operation
- Excellent Gain and Phase Margins
- Common Mode Input Includes Ground
- Zero Deadband Crossover Distortion
- NCV devices are AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



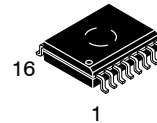
**Figure 1. Representative Block Diagram**



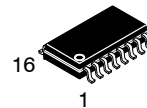
**PDIP-8  
DP1 SUFFIX  
CASE 626**



**PDIP-16  
DP2 SUFFIX  
CASE 648**



**SOIC-16W  
DW SUFFIX  
CASE 751G**



**SOEIAJ-16  
DM2 SUFFIX  
CASE 966**

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

### DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

# TCA0372, TCA0372B, NCV0372B

## MAXIMUM RATINGS

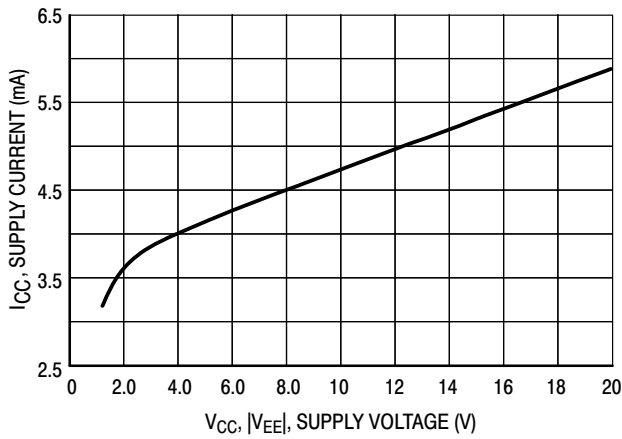
Rating	Symbol	Value	Unit
Supply Voltage (from $V_{CC}$ to $V_{EE}$ )	$V_S$	40	V
Input Differential Voltage Range	$V_{IDR}$	Note 1	V
Input Voltage Range	$V_{IR}$	Note 1	V
Junction Temperature (Note 2)	$T_J$	+150	°C
Operating Temperature Range	$T_A$	-40 to +125	°C
Storage Temperature Range	$T_{stg}$	-55 to +150	°C
DC Output Current	$I_O$	1.0	A
Peak Output Current (Nonrepetitive)	$I_{(max)}$	1.5	A
Thermal Resistance, Junction-to-Air Case 626 Case 648 Case 751G	$R_{\theta JA}$	137 72 80	°C/W
Thermal Resistance, Junction-to-Case Case 626 Case 648 Case 751G	$R_{\theta JC}$	23 10 12	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

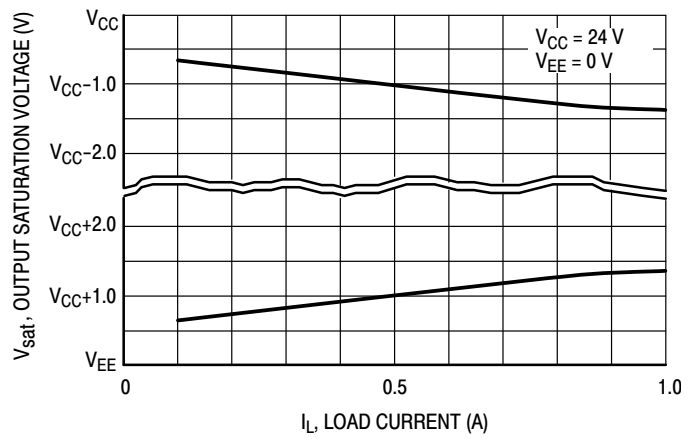
1. Either or both input voltages should not exceed the magnitude of  $V_{CC}$  or  $V_{EE}$ .
2. Power dissipation must be considered to ensure maximum junction temperature ( $T_J$ ) is not exceeded.



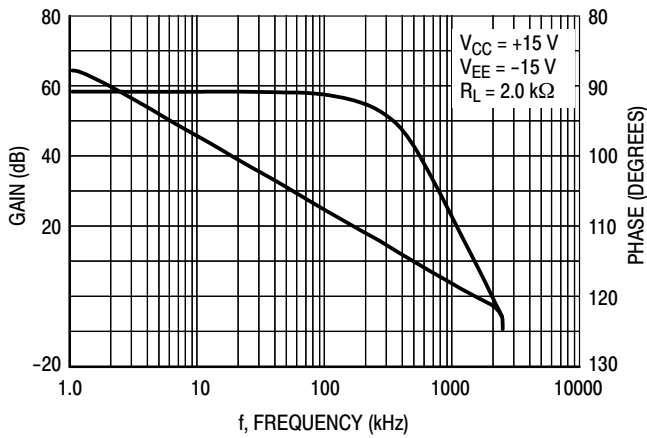
# TCA0372, TCA0372B, NCV0372B



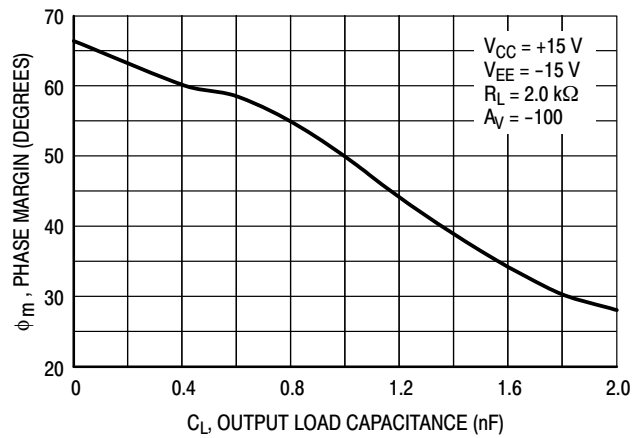
**Figure 2. Supply Current versus Supply Voltage with No Load**



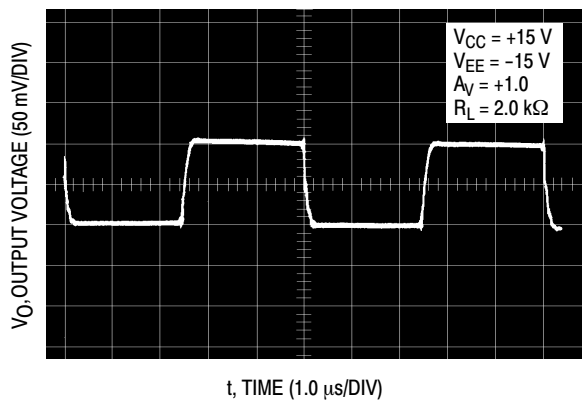
**Figure 3. Output Saturation Voltage versus Load Current**



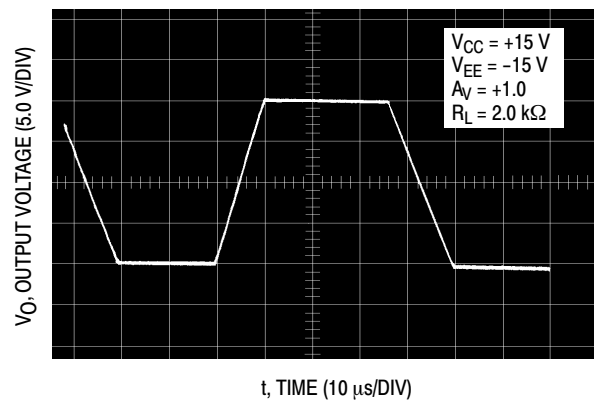
**Figure 4. Voltage Gain and Phase versus Frequency**



**Figure 5. Phase Margin versus Output Load Capacitance**

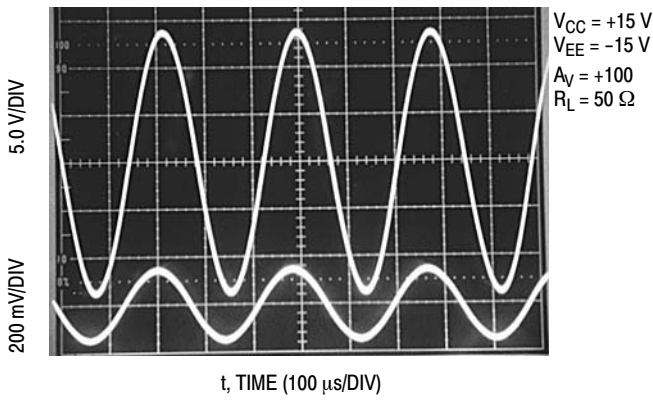


**Figure 6. Small Signal Transient Response**

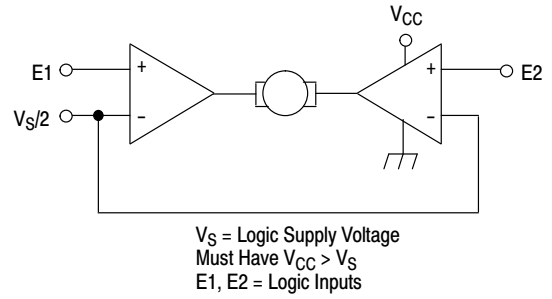


**Figure 7. Large Signal Transient Response**

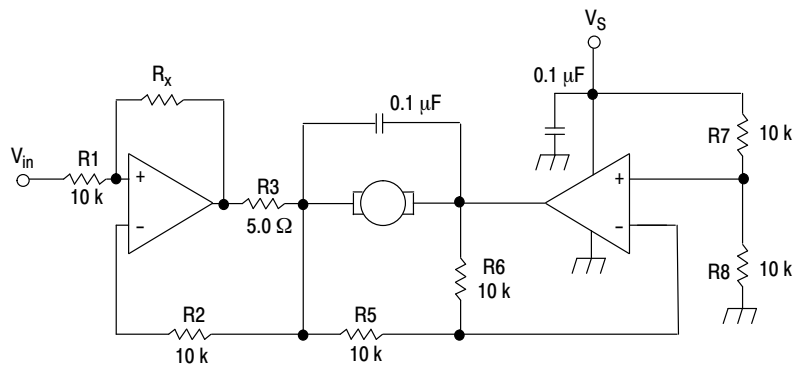
# TCA0372, TCA0372B, NCV0372B



**Figure 8. Sine Wave Response**



**Figure 9. Bidirectional DC Motor Control with Microprocessor-Compatible Inputs**



For circuit stability, ensure that  $R_x > \frac{2R_3 \cdot R_1}{R_M}$  where,  $R_M$  = internal resistance of motor.  
 The voltage available at the terminals of the motor is:  $V_M = 2(V_1 - \frac{V_S}{2}) + |R_{O1}| \cdot I_M$   
 where,  $|R_{O1}| = \frac{2R_3 \cdot R_1}{R_x}$  and  $I_M$  is the motor current.

**Figure 10. Bidirectional Speed Control of DC Motors**

# TCA0372, TCA0372B, NCV0372B

## ORDERING INFORMATION

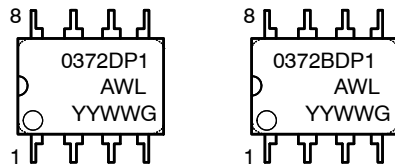
Device	Package	Shipping†
TCA0372DWG	SOIC-16W (Pb-Free)	47 Units / Rail
TCA0372DWR2G	SOIC-16W (Pb-Free)	1000 / Tape & Reel
TCA0372BDWR2G	SOIC-16W (Pb-Free)	1000 / Tape & Reel
NCV0372BDWR2G*	SOIC-16W (Pb-Free)	1000 / Tape & Reel
TCA0372DP1G	PDIP-8 (Pb-Free)	50 Units / Rail
TCA0372BDP1G	PDIP-8 (Pb-Free)	50 Units / Rail
TCA0372DP2G	PDIP-16 (Pb-Free)	25 Units / Rail
TCA0372DM2ELG	SOEIAJ-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*AEC-Q100 Qualified and PPAP Capable

## MARKING DIAGRAMS

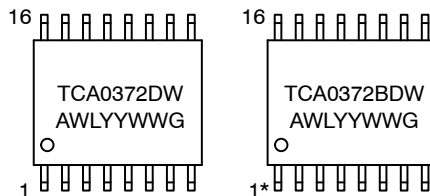
**PDIP-8**  
**DP1 SUFFIX**  
**CASE 626**



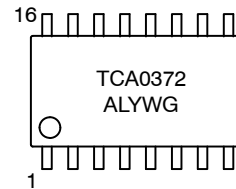
**PDIP-16**  
**DP2 SUFFIX**  
**CASE 648**



**SOIC-16W**  
**DW SUFFIX**  
**CASE 751G**



**SOEIAJ-16**  
**DM2 SUFFIX**  
**CASE 966**

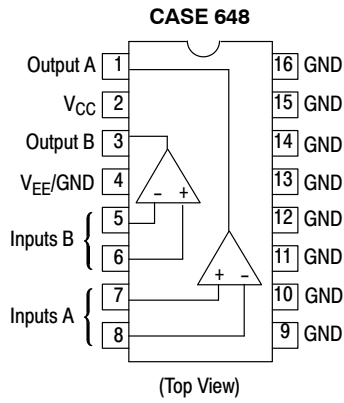


\*Also applies to NCV0372BDWR2G.

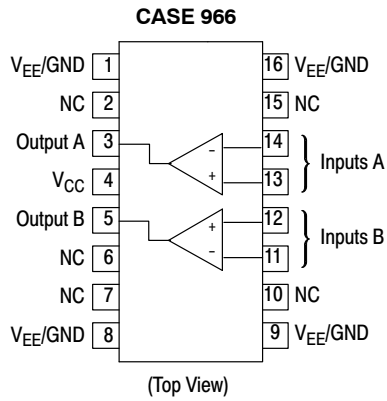
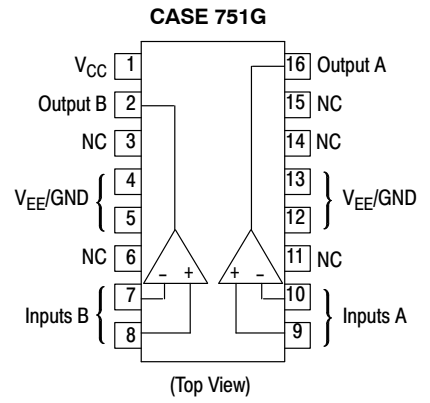
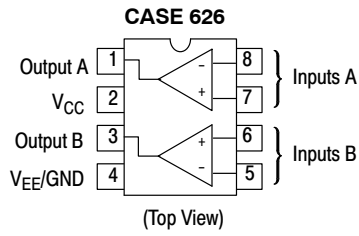
A = Assembly Location  
 WL, L = Wafer Lot  
 YY, Y = Year  
 WW, W = Work Week  
 G = Pb-Free Package

# TCA0372, TCA0372B, NCV0372B

## PIN CONNECTIONS



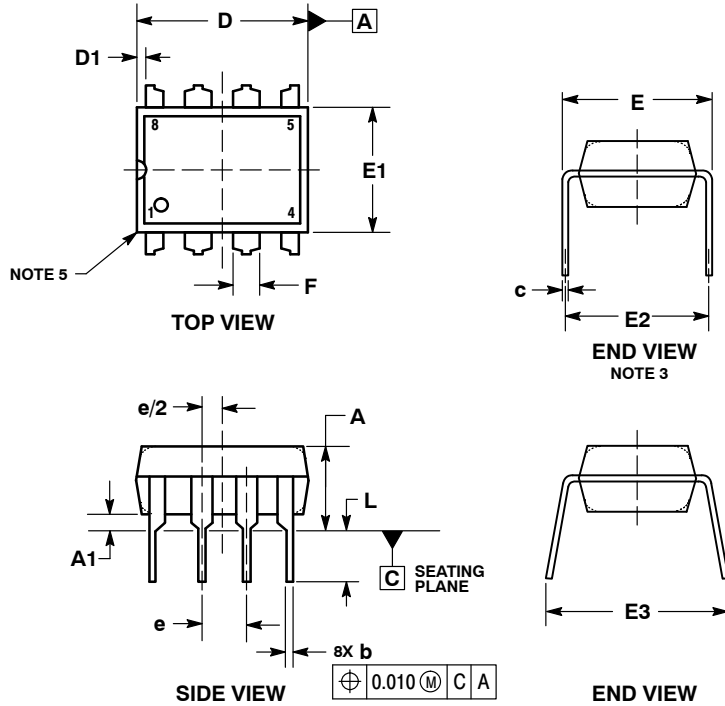
\*Pins 4 and 9 to 16 are internally connected.



# TCA0372, TCA0372B, NCV0372B

## PACKAGE DIMENSIONS

### PDIP-8 DP1 SUFFIX CASE 626-05 ISSUE M

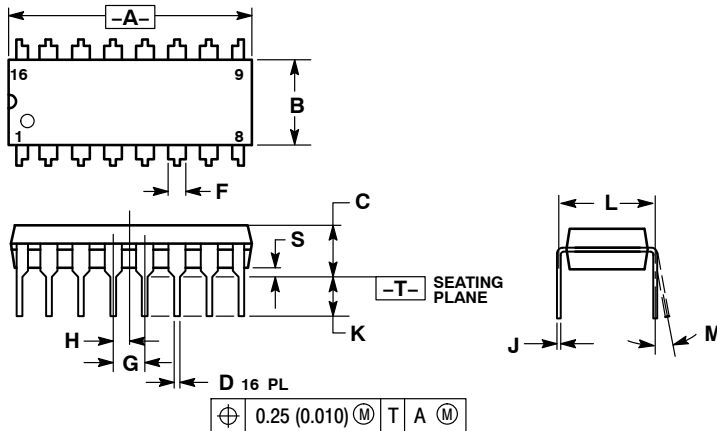


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION E IS MEASURED WITH THE LEADS RESTRAINED PARALLEL AT WIDTH E2.
4. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	----	----	0.210	----	----	5.33
A1	0.015	----	----	0.38	----	----
b	0.014	0.018	0.022	0.35	0.46	0.56
C	0.008	0.010	0.014	0.20	0.25	0.36
D	0.355	0.365	0.400	9.02	9.27	10.02
D1	0.005	----	----	0.13	----	----
E	0.300	0.310	0.325	7.62	7.87	8.26
E1	0.240	0.250	0.280	6.10	6.35	7.11
E2	0.300 BSC			7.62 BSC		
E3	----	----	0.430	----	----	10.92
e	0.100 BSC			2.54 BSC		
L	0.115	0.130	0.150	2.92	3.30	3.81

### PDIP-16 DP2 SUFFIX CASE 648-08 ISSUE T



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

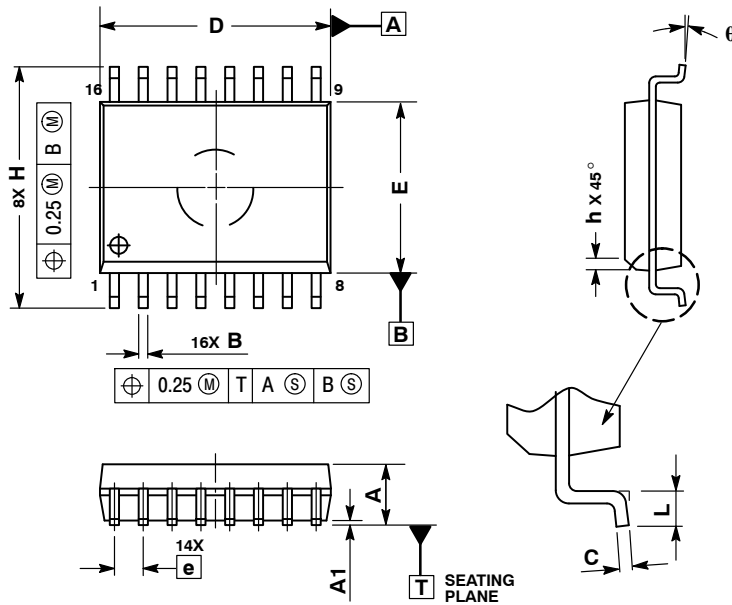
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01



# TCA0372, TCA0372B, NCV0372B

## PACKAGE DIMENSIONS

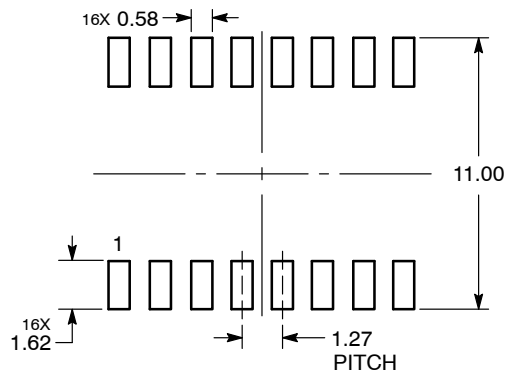
SOIC-16 WB  
CASE 751G-03  
ISSUE D



- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
q	0 °	7 °

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.